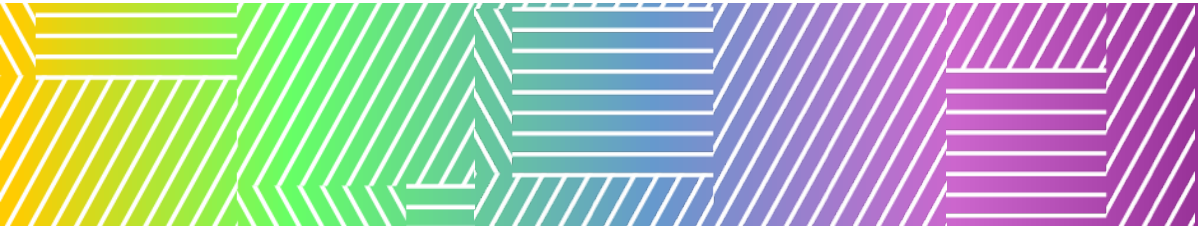


A decorative graphic consisting of several vertical, parallel lines of varying colors (purple, blue, green, yellow, orange, red) on the left side of the page.

Eteros Technologies

On time. First time right. Every time.



A Quick Introduction



Who We Are

- 4.5 year-old company
- 130+ years combined leadership experience
- Provider of quality end-to-end semiconductor engineering services
- Experts in Automotive, AI & Datacenter SoCs
- Growth track record built on our compelling promise

On time. First time right. Every time.



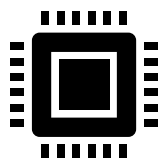
Why Talk to Us?

Proven track record in Automotive,
AI & Datacenter SoCs

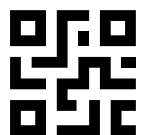


25 customers and counting.

From startups to large caps world-wide.



16+ tape-outs in 4 years.



3nm, 5nm, 7nm nodes.

Netlist to GDS, DFT, analog design, layout.



Why Talk To Us?

Customer-centric model for on-time,
on-cost delivery



**Right expertise + right sized team
+ streamlined program management.**
To solve any customer problem.



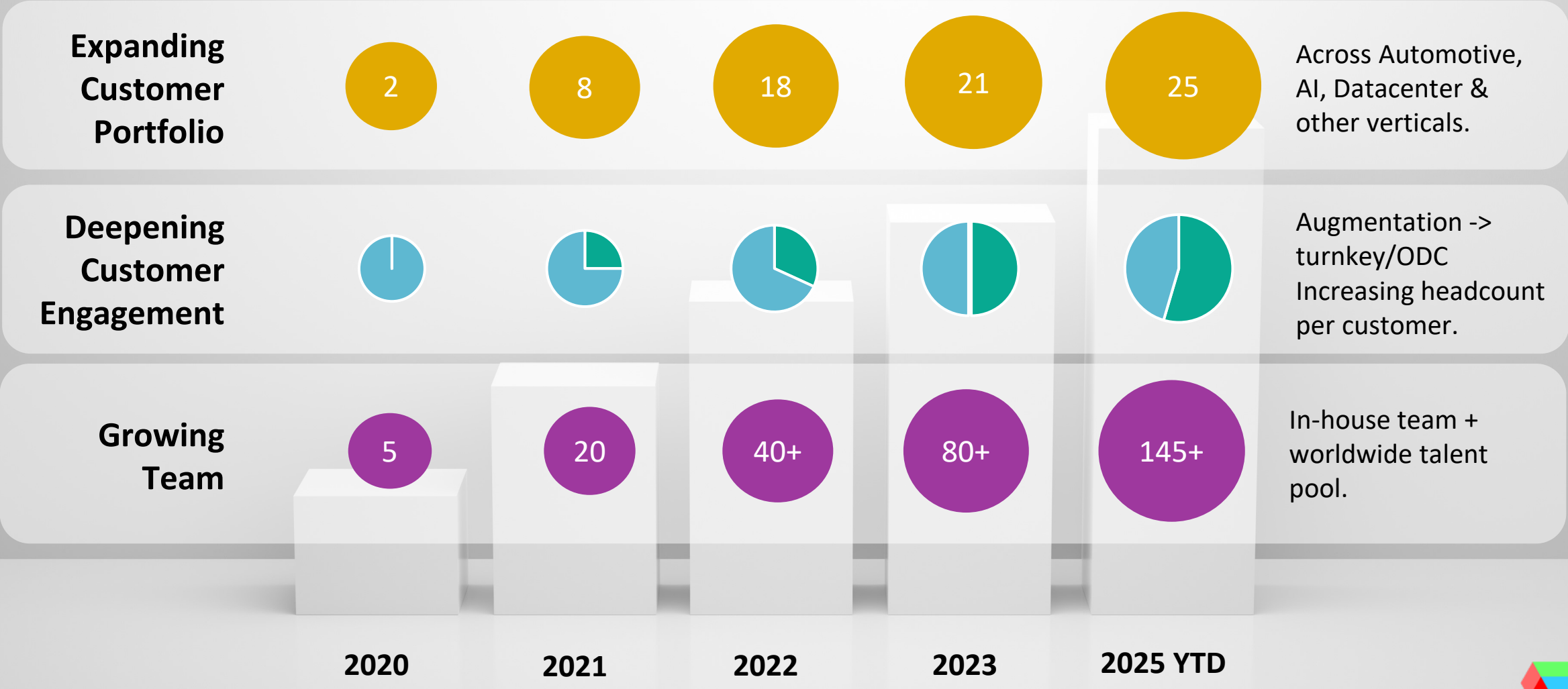
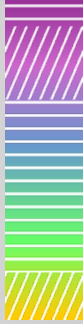
145+ engineers deployed globally.



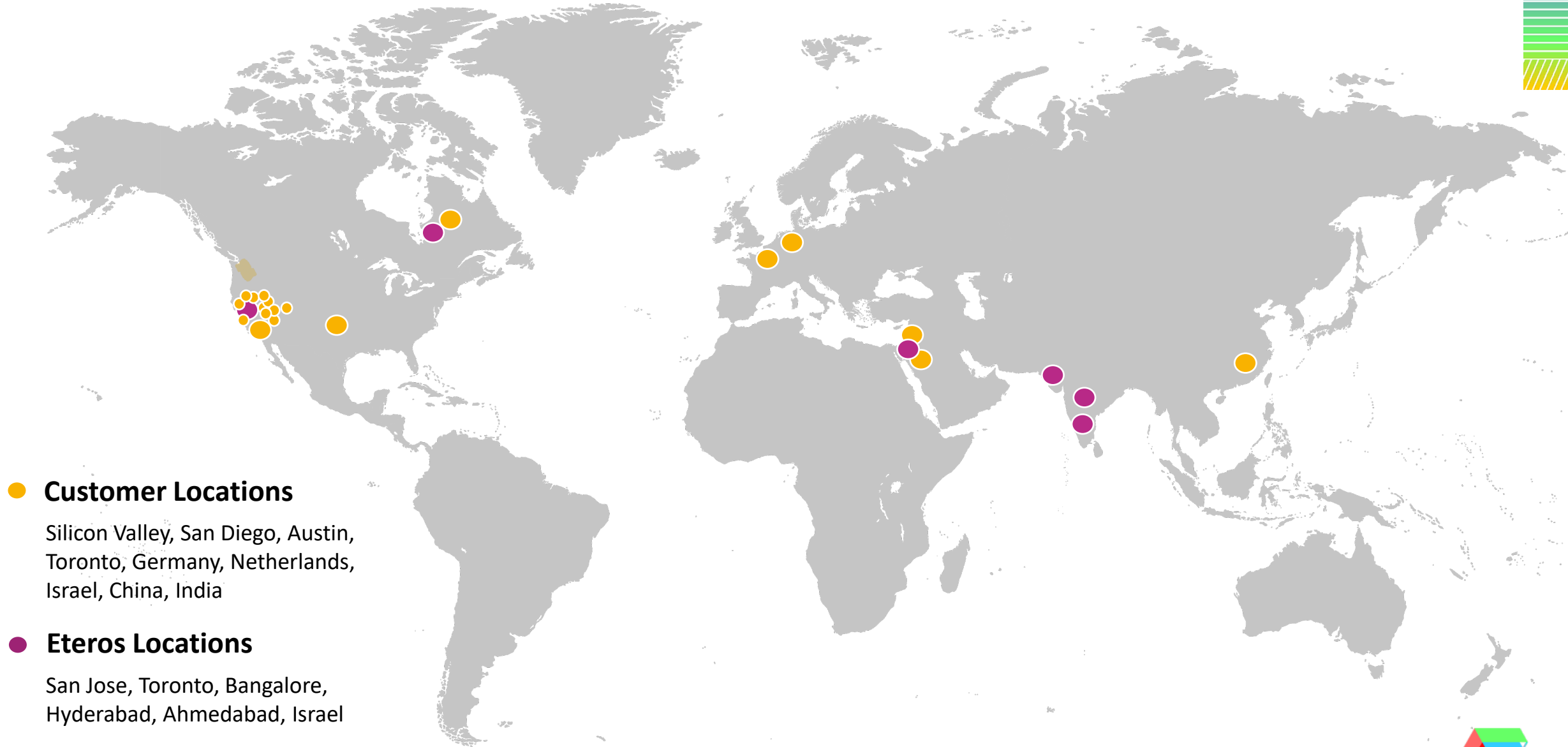
On Time. First time right. Every time.

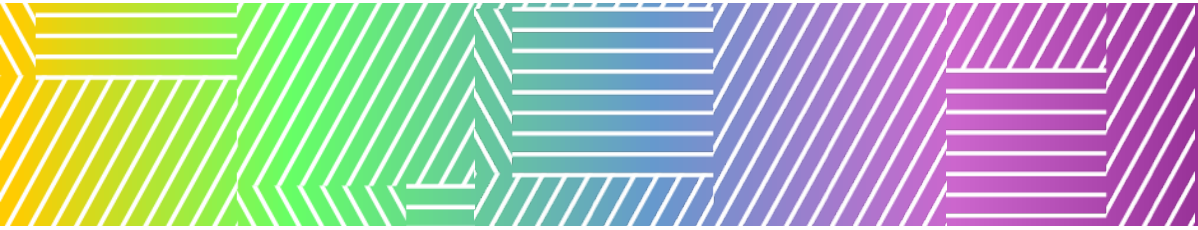


Steady Growth Over 4 Years



Global Footprint for Nearshore Support





What We Do

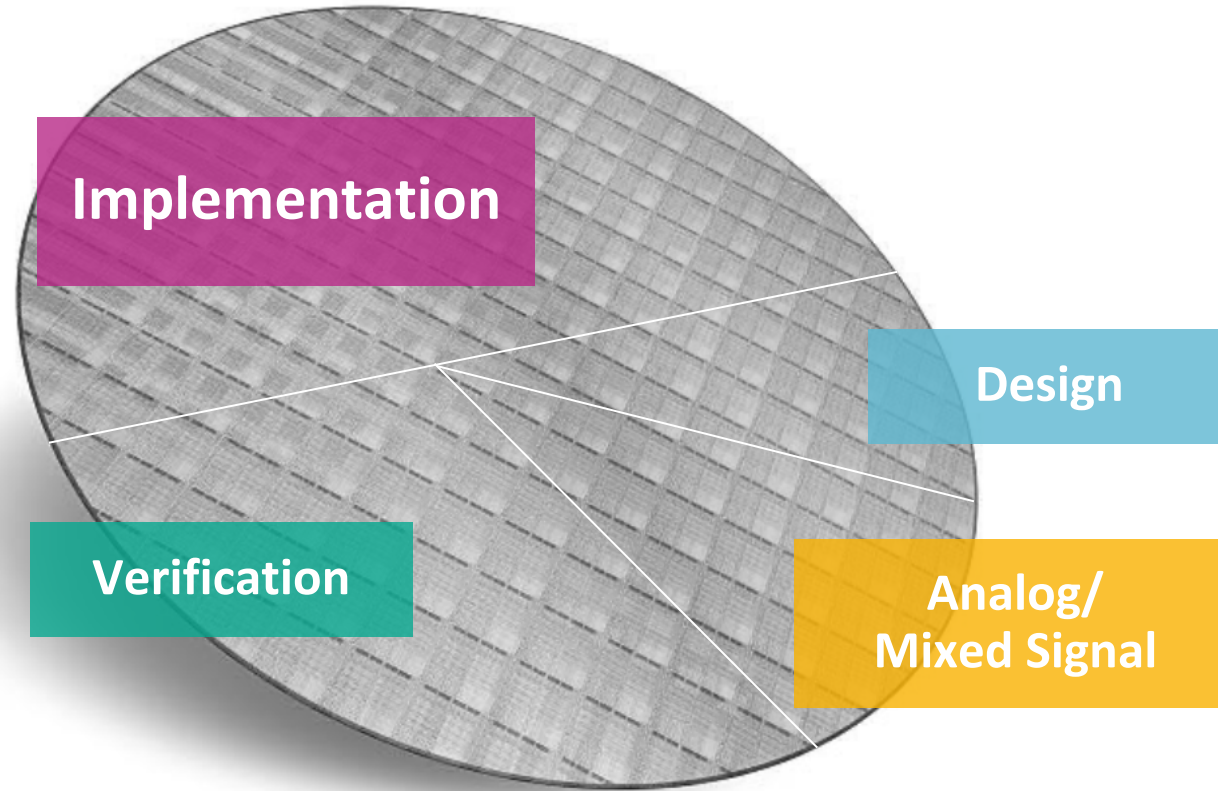


End-to-End Silicon Design Services



- Flow & Methodology Dev
- Netlist -> GDS
- Constraints Development
- DFT & Post-Silicon Debug
- Physical verification
- Sign-off

- IP Verification: PCIe, USB, MIPI, DDR, ARM CPU & BUS protocols
- Subsystem Verification
- SoC
- SV/UVM



- RTL
- Foundation IP
- Custom Std. Cell Dev & Char
- DACs/ADCs/PLL
- Power Management
- High Speed Serdes
- IP Porting
- Custom Layout



Business Models Tailored to Your Needs

Turnkey Project Execution

- SoW driven • On customer network with customer tooling OR @ Eteros
- Streamlined project management up to on-time delivery

Dedicated Design Center

- Dedicated team per customer roadmap • Flexibility & scalability
- Delivery responsibility with Eteros • Virtual team or physical office

Staff Augmentation

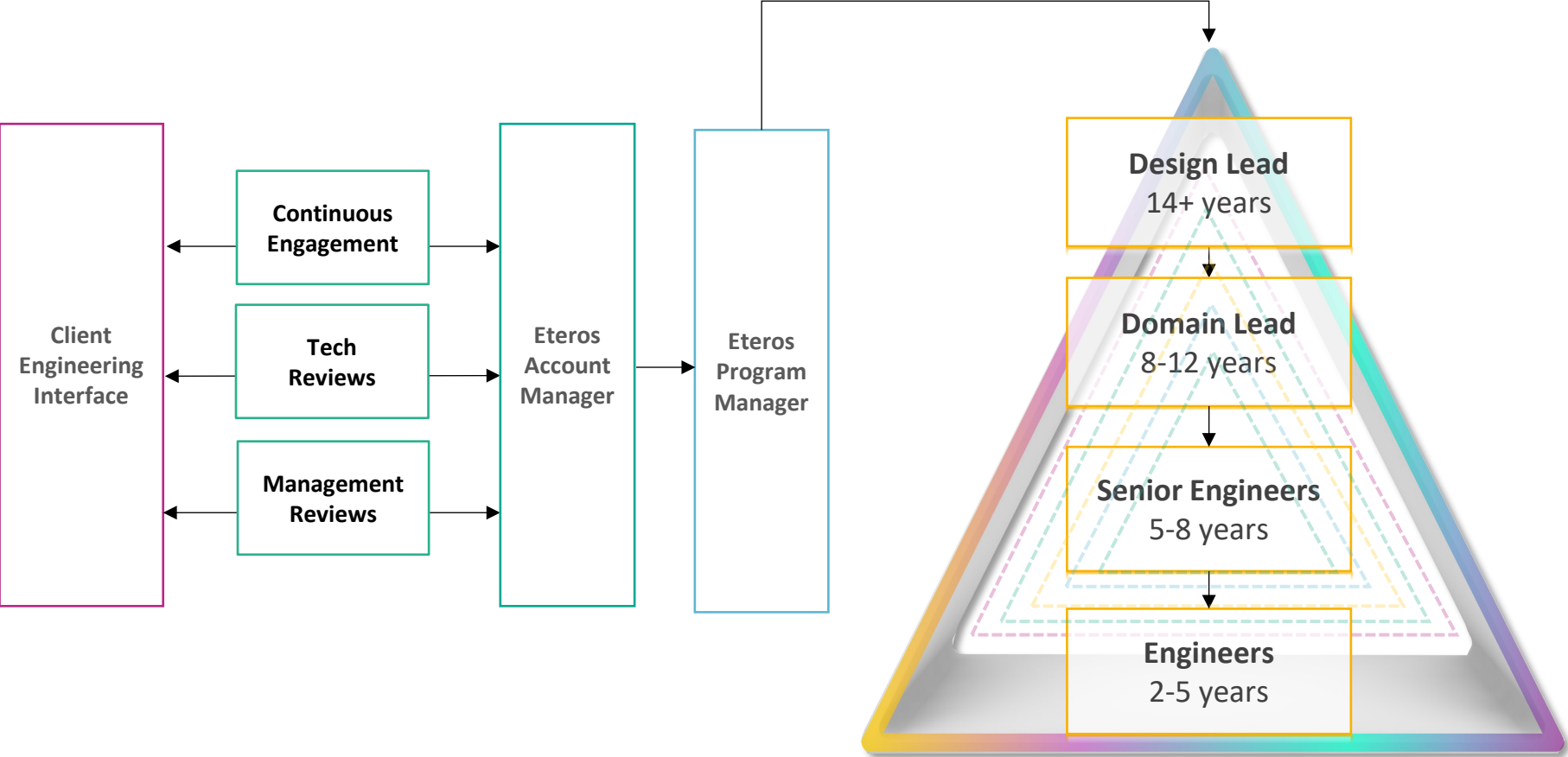
- Support customer's existing engineering teams
- Eteros engineers interact directly with counterparts

Build Operate Transfer

- High-caliber team for specific customer needs
- Execute project for fixed duration • Transfer team to customer

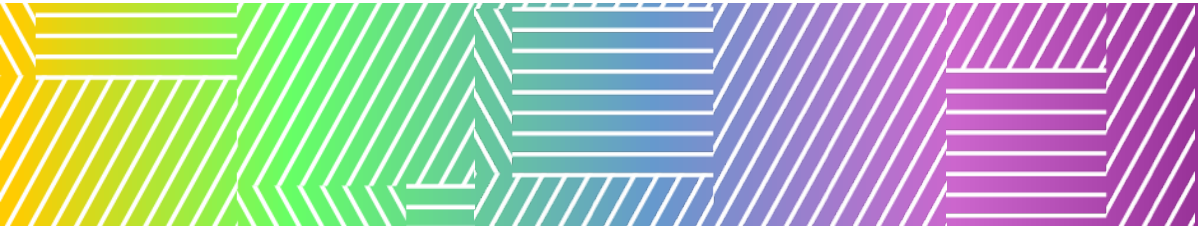


Engagement Model for On-Time, On-Cost Delivery



Eteros Team: Right Expertise + Right Sized Team





Our Leadership



Experienced Leadership



Jai Durgam, Co-Founder

30+ years, GlobalFoundries, Synopsys, Scintera Networks, National Semi



Vishal Abrol, Co-Founder

25+ years, Cadence, Mentor Graphics, Hughes



Sudheer Reddy, Co-Founder

20+ years, Intel, Aricent, ST Microelectronics, Qualcomm



Manjunath V, Physical Design

25+ years, Signoff Semi Open-Silicon, Cadence, Intel



Dharanendra K, Verification

22+ years, Cypress, Cisco, IBM



Mohd. Maaz, Layout

16+ years, Mirafra, Cyient, National Semi



Ankit Khare, DFT

18+ years, NXP, Qualcomm, ST Microelectronics

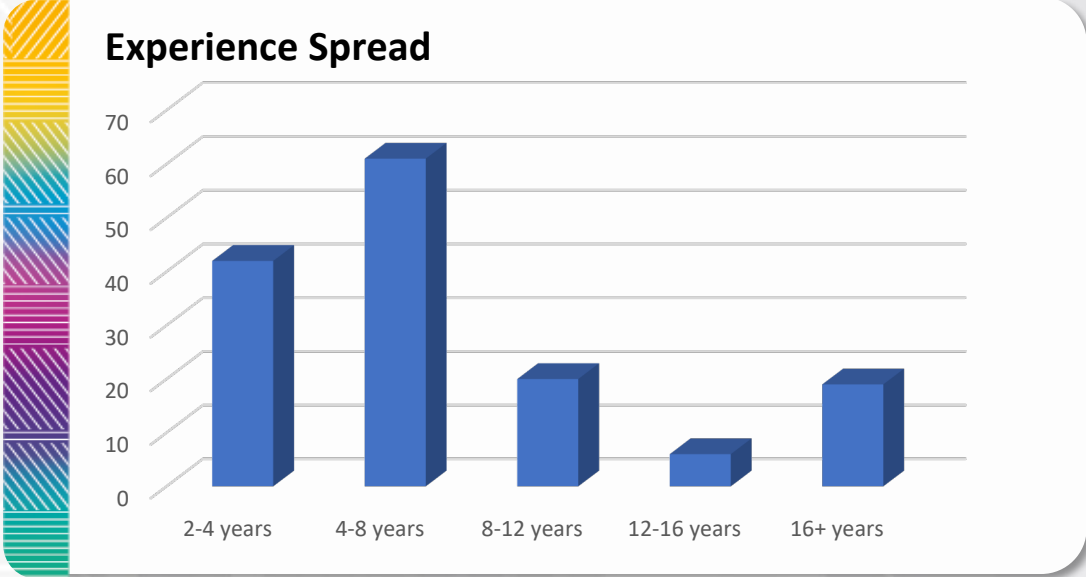


Suresh N, Analog Design

18+ years, SNPS, Intersil, Qualcomm

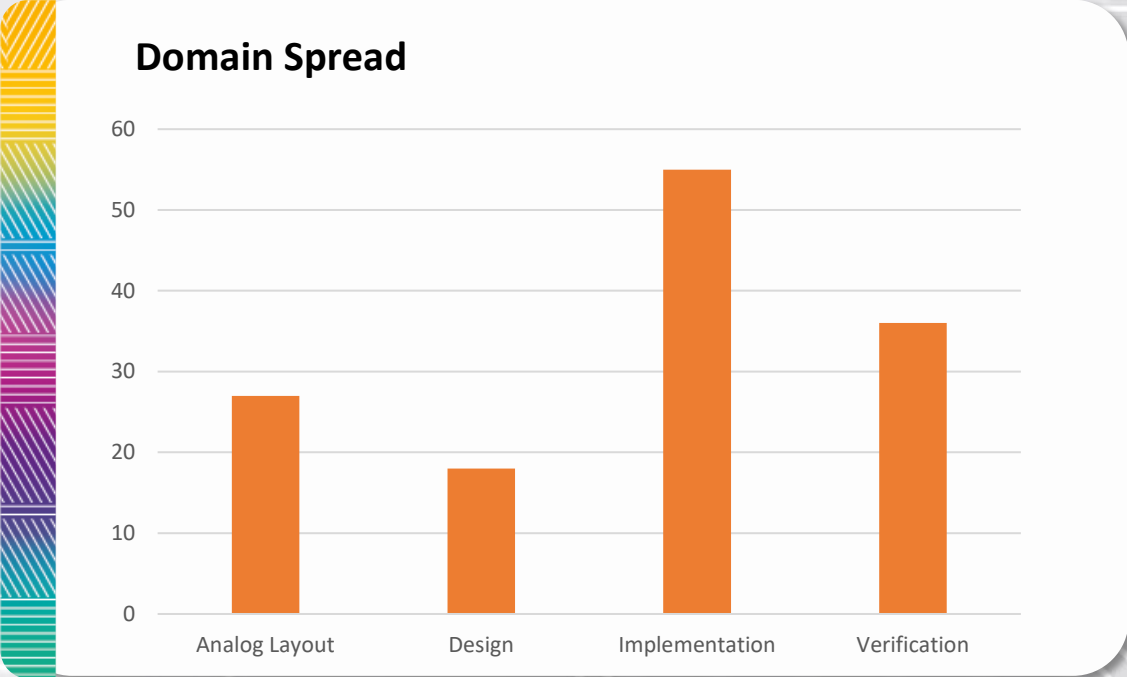


Engineering Depth & Spread

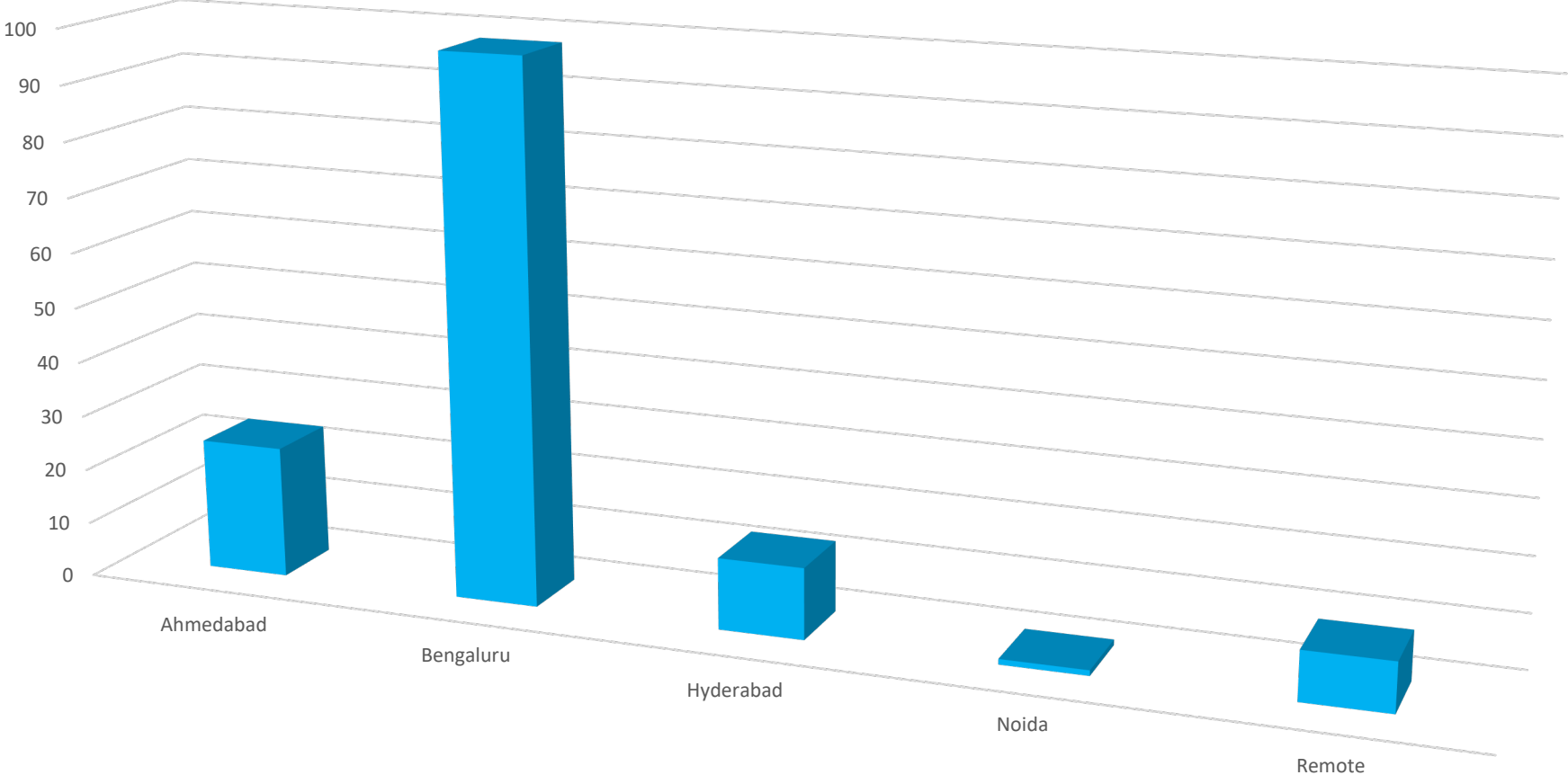


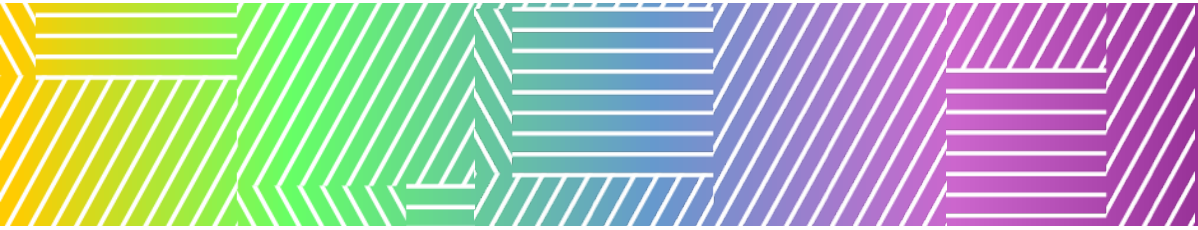
~6.5 Years

Average engineering experience



India Engineering Locations



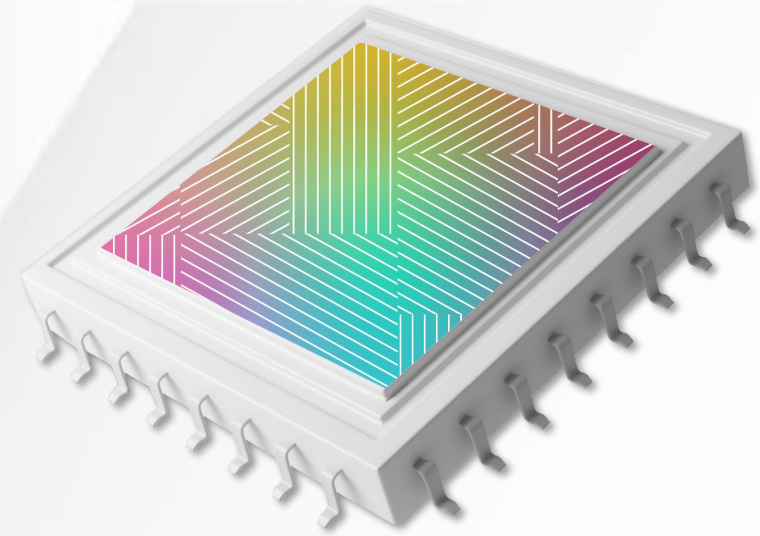


Eteros Advantage



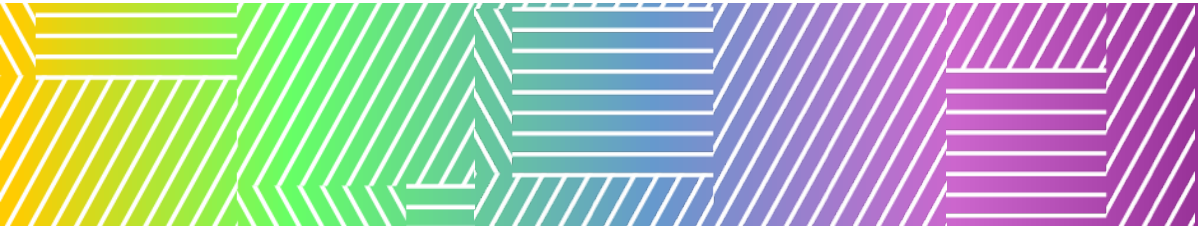
The Eteros Advantage

- End-to-end silicon design
- Experience delivering for top-notch start-ups and large companies
- Proven expertise in Automotive, AI, Datacenter SoCs
- Worldwide talent pool to attract and deploy the best talent on-demand
- Differentiated business model: Right expertise + right-sized teams for on-time on-cost delivery



On Time. First Time Right. Every Time.





From Sub-Systems to SoCs



Areas of Focus: Physical Design and DFT

Physical Design & Sign-off

- Synthesis, Logic Equivalence Checking
- Timing constraints development and validation
- Full-chip Floorplan – Partitioning, IO Layout, Bump/RDL
- Block-level implementation –
- PPA Optimizations, MMMC optimizations
- Block-level and Full-chip Sign-off
 - STA and timing closure
 - IR-Drop, EM, ESD analysis and closure
 - Physical Verification – DRC/LVS/ERC/DFM
 - Define sign-off methodologies
- Full-chip integration and Sign-off
- Methodology development, automation

Design for Test (DFT)

- Defining complete DFT architecture
- Boundary Scan, JTAG, iJTAG implementation
- Scan insertion
 - Hierarchical/Flat strategies
 - Compression, OCC implementation
- ATPG
 - Pattern generation and Simulations (timing/no-timing)
 - Test point insertion, coverage improvement
- Memory BIST generation, integration and simulation
- LBIST generation and integration and simulation
- Test-mode timing constraints generation and timing closure
- Verification at all phases to ensure final sign-off
- Post-SI
 - Tester debug, silicon bring-up
 - Failure analysis assistance and yield improvement



Areas of Focus: Analog

Design

- Technology nodes: 5nm, 7nm, 12nm, 14nm, 16nm and above
- High speed analog layout
 - 56G & 112G Serdes, High-speed TX/RX
 - ADC, DAC, PLLs, LDO, VREG, BGR, PI, PIMX, Oscillators, Sensors etc.
 - DDRs – DDR54, LPDDR4X
- AMS Modelling and AMS Verification

Layout

- AMS, RF Layout, Digital, Custom Digital layout
 - Technologies – 5nm to 180nm and above
 - Foundries – TSMC, GF, SMIC, Samsung
 - IPs – High-speed, RF, High-density, Memories, Standard cells
- AMS CAD
 - Automation and flow development



Areas of Focus: Design Verification

Design Verification

- SOC Level verification
 - Test Plan to Post-Si end-to-end verification
 - Environment creation and automation
 - Testbench/Testcase development
 - Pre-SI verification - Coverage analysis, Regressions
 - Gate-level-Simulations
 - System level validation
 - CPU based verification, cache-coherency
 - Assertions, Assertion based verification
 - C/C++/SV/OVM/UVM based verification
- IP Level verification
 - Feature testing and verification
 - IP to VIP development and integration
 - SOC integration verification
- AMS Verification
 - Digital-on-top and analog-on-top mixed mode
 - AMS modeling and verification
- Flow development, documentation and training

- High-speed protocols
 - USBx, PCIe, SATA, SPI, MIPI, CSI, RapidIO
- Memory interface/SSDs
 - NAND, DDRx, SD, eMMC and flash controllers
- AMBA protocols
 - APB, AHB, AXI and AHB-lite
- Domains
 - 5G NoCs, Modems, Networking, Ethernet
 - Image Processing, Edge computing
 - CPU – ARM, Faraday processor



Contact us



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info@eterostech.com



[LinkedIn](#)





Thank you

धन्यवाद

شكراً

Merci

תודה

谢谢

Toda

Bedankt

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careers@eterostech.com

